

WHAT IS CLAIMED IS:

1. A method for manufacturing a probe card, which comprises a contact provided on a base substrate and electrically coupled to a terminal of an electronic device, for receiving and/or sending a signal from and/or to said electronic device, comprising:

a first contact formation step of forming a first contact of said contacts on a first surface of a first sacrificial substrate;

a second contact formation step of forming a second contact of said contacts of a first surface of a second sacrificial substrate;

a signal transmission line formation step of forming a signal transmission line in said base substrate;

a first contact joining step of attaching said first surface of said first sacrificial substrate to said base substrate and joining said first contact to said signal transmission line; and

a second contact joining step of attaching said first surface of said second sacrificial substrate to said base substrate and joining said second contact to said signal transmission line.

2. A method for manufacturing a probe card as claimed in claim 1 further comprising:

a first sacrificial substrate elimination step of eliminating said first sacrificial substrate after said first contact is coupled to said signal transmission line in said first contact joining step,

wherein after said first sacrificial substrate is eliminated in said first sacrificial substrate elimination step, said first surface of said second sacrificial substrate is attached to said base substrate and said second contact is joined to said signal transmission line in said second contact joining step.

3. A method for manufacturing a probe card as claimed in claim 1, wherein said first contact formation step comprises the steps of:

forming a first penetration hole in said first sacrificial substrate; and

forming first one of said first contacts in order that a first end of said first one of said first contacts is fixed to said first surface of said first sacrificial substrate and a second end of said first one of said first contacts is bent in a direction toward a second surface opposite to said first surface of said first sacrificial substrate to be held freely within said first penetration hole.

4. A method for manufacturing a probe card as claimed in claim 3, wherein said first contact formation step comprises a step of:

forming a second one of said first contacts in order that a first end of said second one of said first contacts is fixed to said first surface of said first sacrificial substrate at a position facing said first one of said first contacts to said first penetration hole and a second end of said second one of said first contacts is bent in said direction toward said second surface of said first sacrificial substrate to be held freely within said first penetration hole.

5. A method for manufacturing a probe card as claimed in claim 4, wherein said first contact formation step comprises a step of:

forming said first and second ones of said first contacts to be substantially symmetrical at two facing sides of said first penetration hole formed in a rectangular shape respectively.

6. A method for manufacturing a probe card as claimed in claim 3, wherein said first contact formation step comprises a step of:

forming a plurality of said first contacts at each of four sides of said first penetration hole formed in a rectangular shape.

7. A method for manufacturing a probe card as claimed in claim 3, wherein said second contact formation step comprises the steps of:

forming a second penetration hole which is larger than an area of said first sacrificial substrate in which said first contact is placed; and

forming said second contact in order that a first end of said second contact is fixed to said first surface of said second sacrificial substrate and a second end of said second contact is bent in a direction toward a second surface opposite to said first surface of said second sacrificial substrate to be held freely within said second penetration hole, and

said second joining step comprises a step of:

attaching said first surface of said second sacrificial substrate to said base substrate in order that said first contact coupled with said signal transmission line is placed within said

second penetration hole and joining said second contact to said signal transmission line.

8. A method for manufacturing a probe card, which comprises a contact provided on a base substrate and electrically coupled to a terminal of an electronic device, for receiving and/or sending a signal from and/or to said electronic device, comprising:

a penetration hole formation step of forming a penetration hole in a sacrificial substrate;

a first contact formation step of forming first one of said contacts in order that a first end of said first one of said contacts is fixed to a first surface of said sacrificial substrate and a second end of said first one of said contacts is bent in a direction toward a second surface opposite to said first surface of said sacrificial substrate to be held freely within said penetration hole;

a second contact formation step of forming second one of said contacts in order that a first end of said second one of said contacts is fixed to said first surface of said sacrificial substrate at a position facing said first one of said contacts to said penetration hole and a second end of said second one of said contacts is bent in said direction toward said second surface of said sacrificial substrate to be held freely within said penetration hole;

a signal transmission line formation step of forming a signal transmission line in said base substrate; and

a contact joining step of attaching said first surface of said sacrificial substrate to said base substrate and joining said first and second ones of said contacts to said signal transmission line.